

Amendments to the Specification:

Page 8, amend the paragraph beginning on line 16 to read as follows:

~~FIG. 1 is a~~ FIGs. 1(a) and 1(b) are perspective view-views showing the overall structure of a vacuum processing apparatus according to the preferred embodiment of the present invention;

Page 8, amend the paragraph beginning on line 19 to read as follows:

~~FIG. 2 is a~~ plan view-FIGs. 2(a) and 2(b) are plan and side views showing the outline structure of the vacuum processing apparatus according to the embodiment of the present invention;

Page 8, amend the paragraph beginning on line 22 to read as follows:

~~FIG. 3 is a~~ FIGs. 3(a) - 3(d) are perspective view-views showing the outline structure of each unit of the vacuum processing apparatus according to the embodiment of the present invention;

Page 9, amend the paragraph beginning on line 19 to read as follows:

~~FIG. 1 is a~~ FIGs. 1(a) and 1(b) are perspective view-views showing the overall structure of a vacuum processing apparatus according to a preferred embodiment of the present invention. FIG. 1(a) is a perspective showing the front side, and (b) is a perspective showing the back side thereof. In this drawing, a vacuum processing apparatus 100 according to the present embodiment is largely divided into two, front and back, blocks. The front side of the vacuum processing apparatus body 100 is an atmospheric block 101 in which a wafer supplied to the apparatus is transferred to a chamber decompressed under atmospheric pressure and supplied to a processing

chamber. The rear side of the apparatus body 100 is composed of a processing block 102. The processing block 102 comprises processing units 103 and 104 having processing chambers being decompressed for processing wafers, a transfer unit 105 for transferring wafers to these processing chambers under reduced pressure, and plural lock chamber units 113 for connecting the transfer unit 105 with the atmospheric block 101, these units capable of being decompressed and maintained at high degree of vacuum, so the processing block is a vacuum block.

Page 11, amend the paragraph beginning on line 19 to read as follows:

~~FIG. 2 is a view of FIGs. 2(a) and 2(b) are views showing the outline of the structure~~ of the vacuum processing chamber 100 according to the embodiment of FIG. 1, in which FIG. 2(a) shows a plan view from above, and FIG. 2(b) shows the view from the side. In these drawings, the atmospheric block 101 disposed on the front side of the vacuum processing apparatus body 100 is for handling (transferring, storing, positioning etc.) the wafers under atmospheric pressure, and the processing block 102 disposed on the rear side of the apparatus body 100 is for transferring and processing wafers under a pressure decompressed from atmospheric pressure and for increasing and decreasing pressure while wafers are disposed therein.

Page 17, amend the paragraph beginning on line 7 to read as follows:

A gap is formed between the rear surface of the box 108 and the ~~frame~~frame 106 of the processing block 102, this gap providing a space in which a user can enter and work on the processing units 104, the transfer chamber 112 and the lock chamber 113, and also providing a space in which the user can confirm the display 202 on the rear of the box 108 and the connection interface unit 201 or enter orders

via the control means etc. Further, means for controlling and displaying information on the operation of apparatuses related to the supply lines are collectively disposed in this space. Thus, the work related to operating the apparatus is facilitated, and the operation efficiency of the apparatus is improved.

Page 19, amend the paragraph beginning on line 10 to read as follows:

~~FIG. 3 is a FIGs. 3(a)-3(d) are perspective view-views~~ showing the outline of the structure of each unit. FIG. 3(a) illustrates the combined status of the processing units. On the other hand, FIGS. 3(b), (c) and (d) illustrate the units separately. FIG. 3(b) shows the etching unit 103, FIG. 3(c) shows the ashing unit 104, and FIG. 3(d) shows the control unit including a MFC (mass flow controller).